



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-04-20
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	LAURENT TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8S105K4U6ATR	B1MG*766XXX7	A	9988	2015-04-20
Amount	UoM	Unit type	ST ECOPACK Grade	
56,11	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x0.55	32	L bend	
Comment	Package: UFQFPN 5X5X0.55 32L 0.5 MM PITCH			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	B1MG*765007					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1,882	mg	supplier	die	Silicon (Si)	7440-21-3		1,745	mg	927205	31102
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0,012	mg	6376	214
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0,040	mg	21254	713
die (s)				supplier	metallization	Tantalum (Ta)	7440-25-7		0,003	mg	1594	53
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0,006	mg	3188	107
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0,011	mg	5845	196
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0,065	mg	34538	1159
Die Attach(ABLEBOND 8290_Henkel)	Other inorganic materials	0,461	mg	Supplier	Glue	Silver	7440-22-4		0,327	mg	709328	5828
Die Attach(ABLEBOND 8290_Henkel)				Supplier	Glue	Bisphenol-F, epoxy resin	9003-36-5		0,022	mg	47722	392
Die Attach(ABLEBOND 8290_Henkel)				Supplier	Glue	Fatty acids, polymers with epichlorohydrin	68475-94-5		0,022	mg	47722	392
Die Attach(ABLEBOND 8290_Henkel)				Supplier	Glue	Gamma Butyrolactone	96-48-0		0,022	mg	47722	392
Die Attach(ABLEBOND 8290_Henkel)				Supplier	Glue	Epoxy Resin	Proprietary		0,022	mg	47722	392
Die Attach(ABLEBOND 8290_Henkel)				Supplier	Glue	Poly(Oxy(methyl-1, 2-ethanedyl))	9046-10-0		0,022	mg	47722	392
Die Attach(ABLEBOND 8290_Henkel)				Supplier	Glue	Copper Oxide	1317-38-0		0,022	mg	47722	392
Die Attach(ABLEBOND 8290_Henkel)				Supplier	Glue	1,4-Bis(2,3-epoxypropoxy) butane	2425-79-8		0,002	mg	4338	36
Encapsulation(EME-G770_Sumitomo)	Other inorganic materials	17,368	mg	Supplier	Epoxy	Epoxy Resin A	Proprietary		0,527	mg	30343	9393
Encapsulation(EME-G770_Sumitomo)				Supplier	Epoxy	Epoxy Resin B	Proprietary		0,527	mg	30343	9393
Encapsulation(EME-G770_Sumitomo)				Supplier	Epoxy	Phenol Resin A	Proprietary		0,527	mg	30343	9393
Encapsulation(EME-G770_Sumitomo)				Supplier	Epoxy	Phenol Resin B	Proprietary		0,527	mg	30343	9393
Encapsulation(EME-G770_Sumitomo)				Supplier	Epoxy	Metal Hydroxide	Proprietary		0,264	mg	15200	4705
Encapsulation(EME-G770_Sumitomo)				Supplier	Epoxy	Carbon Black	1333-86-4		0,053	mg	3052	945
Encapsulation(EME-G770_Sumitomo)				Supplier	Epoxy	Silica Fused	60676-86-0		14,943	mg	860375	266335
Bonding wire(Au wire_MKE)	Other inorganic materials	0,258	mg	Supplier	Wire	Gold	7440-57-5		0,258	mg	999613	4598
Bonding wire(Au wire_MKE)				Supplier	Wire	Palladium	7440-05-3		0,000	mg	387	2
Finishing(Pure Tin_Nuonengda)	Other inorganic materials	1,604	mg	Supplier	Connection coating	Tin	7440-31-5		1,604	mg	1000000	28589
Leadframe(Mitsui C7+AG)	Other inorganic materials	34,533	mg	Supplier	Alloy	Copper	7440-50-8		32,790	mg	949527	584429
Leadframe(Mitsui C7+AG)				Supplier	Alloy	Nickel	7440-57-5		1,000	mg	28958	17823
Leadframe(Mitsui C7+AG)				Supplier	Alloy	Silicon	7440-21-3		0,216	mg	6255	3850
Leadframe(Mitsui C7+AG)				Supplier	Alloy	Magnesium	7440-50-8		0,051	mg	1477	909
Leadframe(Mitsui C7+AG)				Supplier	Alloy	Silver	7440-22-4		0,476	mg	13784	8484